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L3: Entry 1 of 1

File: DWPI

Oct 30, 1997

DERWENT-ACC-NO: 1997-536112

DERWENT-WEEK: 200440

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TITLE: Substrate wafer wet treatment device - has nozzle system supplying treatment fluid to container holding substrate wafers for providing uniform laminar flow

INVENTOR: OSHINOWO, J; WEBER, M

PRIORITY-DATA: 1996DE-1016402 (April 24, 1996), 1996DE-1054903 (April 24, 1996), 1996DE-1055219 (April 24, 1996)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
WO 9740524 A1	October 30, 1997	G	026	H01L021/00
DE 19616402 A1	November 6, 1997		008	H01L021/302
DE 19654903 A1	November 13, 1997		007	H01L021/302
DE 19654903 C2	September 24, 1998		000	H01L021/302
EP 895655 A1	February 10, 1999	G	000	H01L021/00
US 5921257 A	July 13, 1999		000	B08B003/02
JP 11510965 W	September 21, 1999		024	H01L021/306
US 5992431 A	November 30, 1999		000	B08B003/10
KR 2000010575 A	February 15, 2000		000	H01L021/00
DE 19655219 A1	July 12, 2001		000	H01L021/302
DE 19616402 C2	November 29, 2001		000	H01L021/302
TW 446575 A	July 21, 2001		000	B01J019/00
KR 316823 B	February 19, 2002		000	H01L021/00
EP 1239512 A2	September 11, 2002	G	000	H01L021/00
DE 19655219 C2	November 6, 2003		000	H01L021/302
EP 895655 B1	February 18, 2004	G	000	H01L021/00
DE 59711318 G	March 25, 2004		000	H01L021/00

895655 B1 , DE 59711318 G INT-CL (IPC): B01 J 19/00; B05 B 1/00; B08 B 3/02; B08 B 3/10; C23 G 3/00; C23 G 5/04; H01 L 21/00; H01 L 21/302; H01 L 21/304; H01 L 21/306

Full	Title	Citation	Front	Review	Classification	Date	Reference	Documents	Claim
------	-------	----------	-------	--------	----------------	------	-----------	-----------	-------

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Term	Documents
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"5921257".DWPI.	1
(5921257).DWPI.	1

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L3: Entry 1 of 1

File: DWPI

Oct 30, 1997

DERWENT-ACC-NO: 1997-536112

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TITLE: Substrate wafer wet treatment device - has nozzle system
supplying treatment fluid to container holding substrate wafers for
providing uniform laminar flow

INVENTOR: OSHINOWO, J; WEBER, M

PATENT-ASSIGNEE:

ASSIGNEE	CODE
STEAG MICROTECH GMBH	STGG
STEAG MICROTECH GMBH STERNEFELS	STGG
SCP GERMANY GMBH	SCPGN

PRIORITY-DATA: 1996DE-1016402 (April 24, 1996), 1996DE-1054903 (April
24, 1996), 1996DE-1055219 (April 24, 1996)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> WO 9740524 A1	October 30, 1997	G	026	H01L021/00
<input type="checkbox"/> DE 19616402 A1	November 6, 1997		008	H01L021/302
<input type="checkbox"/> DE 19654903 A1	November 13, 1997		007	H01L021/302
<input type="checkbox"/> DE 19654903 C2	September 24, 1998		000	H01L021/302
<input type="checkbox"/> EP 895655 A1	February 10, 1999	G	000	H01L021/00
<input type="checkbox"/> US 5921257 A	July 13, 1999		000	B08B003/02
<input type="checkbox"/> JP 11510965 W	September 21, 1999		024	H01L021/306
<input type="checkbox"/> US 5992431 A	November 30, 1999		000	B08B003/10
<input type="checkbox"/> KR 2000010575 A	February 15, 2000		000	H01L021/00
<input type="checkbox"/> DE 19655219 A1	July 12, 2001		000	H01L021/302
<input type="checkbox"/> DE 19616402 C2	November 29, 2001		000	H01L021/302
<input type="checkbox"/> TW 446575 A	July 21, 2001		000	B01J019/00
<input type="checkbox"/> KR 316823 B	February 19, 2002		000	H01L021/00

☐ EP 1239512 A2 September 11, 2002 G 000 H01L021/00
☐ DE 19655219 C2 November 6, 2003 000 H01L021/302
☐ EP 895655 B1 February 18, 2004 G 000 H01L021/00
☐ DE 59711318 G March 25, 2004 000 H01L021/00

DESIGNATED-STATES: CA CN CZ IL JP KR SG AT BE CH DE DK ES FI FR GB GR
 IE IT LU MC NL PT SE AT BE DE FR GB IT NL AT BE DE FR GB IT NL AT BE DE
 FR GB IT NL

CITED-DOCUMENTS:DE 4413077; US 4092176 ; US 4753258 ; US 5474616 ; US
 5488964 ; US 5520205

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
WO 9740524A1	March 27, 1997	1997WO-EP01580	
DE 19616402A1	April 24, 1996	1996DE-1016402	
DE 19616402A1		DE 19654903	Div in
DE 19654903A1	April 24, 1996	1996DE-1016402	Div ex
DE 19654903A1	April 24, 1996	1996DE-1054903	
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DE 19654903C2	April 24, 1996	1996DE-1016402	Div ex
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EP 895655A1	March 27, 1997	1997EP-0915453	
EP 895655A1	March 27, 1997	1997WO-EP01580	
EP 895655A1		WO 9740524	Based on
US 5921257A	December 6, 1996	1996US-0762199	
JP 11510965W	March 27, 1997	1997JP-0537651	
JP 11510965W	March 27, 1997	1997WO-EP01580	
JP 11510965W		WO 9740524	Based on
US 5992431A	December 6, 1996	1996US-0762199	Div ex
US 5992431A	April 7, 1998	1998US-0056586	
KR2000010575A	March 27, 1997	1997WO-EP01580	
KR2000010575A	October 22, 1998	1998KR-0708443	
KR2000010575A		WO 9740524	Based on
DE 19655219A1	April 24, 1996	1996DE-1016402	Div ex
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DE 19616402C2		DE 19654903	Div in
DE 19616402C2		DE 19655219	Div in
TW 446575A	April 10, 1997	1997TW-0104566	
KR 316823B	March 27, 1997	1997WO-EP01580	
KR 316823B	October 22, 1998	1998KR-0708443	

KR 316823B		KR2000010575	Previous Publ.
KR 316823B		WO 9740524	Based on
EP 1239512A2	March 27, 1997	1997EP-0915453	Div ex
EP 1239512A2	March 27, 1997	2002EP-0005774	
EP 1239512A2		EP 895655	Div ex
DE 19655219C2	April 24, 1996	1996DE-1016402	Div ex
DE 19655219C2	April 24, 1996	1996DE-1055219	
DE 19655219C2		DE 19616402	Div ex
EP 895655B1	March 27, 1997	1997EP-0915453	
EP 895655B1	March 27, 1997	1997WO-EP01580	
EP 895655B1	March 27, 1997	2002EP-0005774	Related to
EP 895655B1		EP 1239512	Related to
EP 895655B1		WO 9740524	Based on
DE 59711318G	March 27, 1997	1997DE-0511318	
DE 59711318G	March 27, 1997	1997EP-0915453	
DE 59711318G	March 27, 1997	1997WO-EP01580	
DE 59711318G		EP 895655	Based on
DE 59711318G		WO 9740524	Based on

895655 B1 , DE 59711318 G INT-CL (IPC): B01 J 19/00; B05 B 1/00; B08 B 3/02; B08 B 3/10; C23 G 3/00; C23 G 5/04; H01 L 21/00; H01 L 21/302; H01 L 21/304; H01 L 21/306

ABSTRACTED-PUB-NO: US 5921257A
BASIC-ABSTRACT:

The device has a container (1) holding a number of substrate wafers, supplied with a treatment fluid for the latter via a nozzle system with a number of nozzles (7), for providing a uniform laminar flow pattern within the container.

The nozzles may have different spray angles (8,9) and are arranged in a matrix pattern across the base of the container, with some nozzles providing a fan-shaped spray while the others provide a conical spray.

ADVANTAGE - Ensures uniform distribution of treatment fluid across substrate wafer.

ABSTRACTED-PUB-NO:

US 5992431A
EQUIVALENT-ABSTRACTS:

The device has a container (1) holding a number of substrate wafers, supplied with a treatment fluid for the latter via a nozzle system with a number of nozzles (7), for providing a uniform laminar flow pattern within the container.

The nozzles may have different spray angles (8,9) and are arranged in a matrix pattern across the base of the container, with some nozzles providing a fan-shaped spray while the others provide a conical spray.

ADVANTAGE - Ensures uniform distribution of treatment fluid across substrate wafer.

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ADVANTAGE - Ensures uniform distribution of treatment fluid across substrate wafer.

WO 9740524A

CHOSEN-DRAWING: Dwg.1/3

TITLE-TERMS: SUBSTRATE WAFER WET TREAT DEVICE NOZZLE SYSTEM SUPPLY
TREAT FLUID CONTAINER HOLD SUBSTRATE WAFER UNIFORM LAMINA FLOW

DERWENT-CLASS: P42 P43 U11

EPI-CODES: U11-F02A1;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1997-446271

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